



Customar Approval:

SPECIFICATION FOR LCD MODULE MODULE NO: YB-TG320240S22B-N-A0

Doc.Version:00

Customer Approvar.	
□ Accept	□ Reject

YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	位张琛	2019/8/29
Check	Mechanical Engineer	- A B	2019/8/29
Verify		邓箬刚	2019/8/29
Approval	\sim	20 TA	2019/8/29
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APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D

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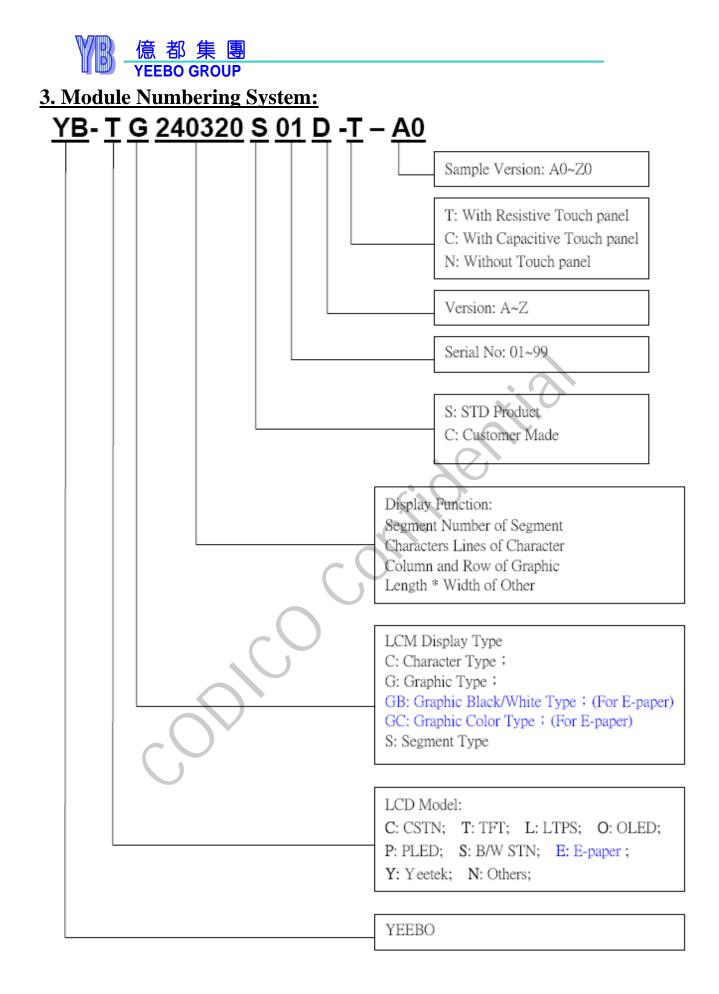
1. Revision History

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY		
A0	00	2019-08-29	SPEC ONLY	First issue	W.J.C/Z.J.Q		
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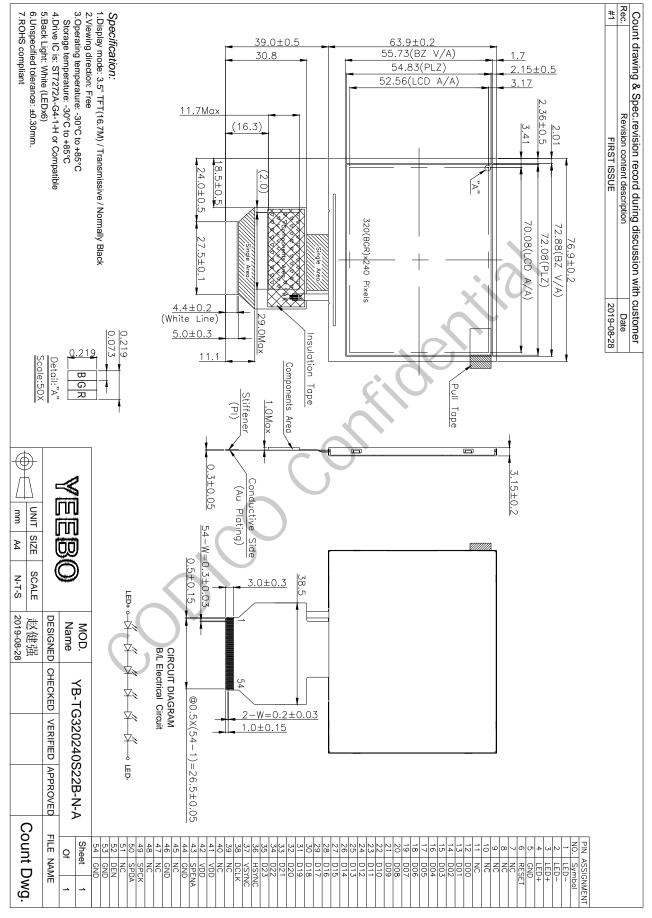


4. General Specification:

ITEM	CONTENTS
Module Size	76.9 (W) * 63.9 (H) * 3.15(T) mm
Module Size(With FPC)	76.9 (W) *102.9 (H) * 3.15(T) mm
Display Size(Diagonal)	3.5 inch
Display Format	320(BGR) * 240 Pixels
Active Area	70.08(W) * 52.56(H) mm
Pixel Pitch	0.219 * 0.219 mm
LCD Type	TFT(262K) / Transmissive / Normally Black
Viewing Direction (Gray Inversion)	Free
Controller IC	ST7272A-G4-1-H
Weight	TBD



5. LCM drawing:



Module P/N:YB-TG320240S22B-N-A0 Doc.Version:00



<u>6. Electrical Characteristics</u>

6-1 Absolute Maximum Ratings

(Ta=25°C GND=0V)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Power Supply Voltage	VCC-GND	-0.3	-	+4.0	Volt	Note1
Operating Temperature	Topr	-30	-	+85	°C	-
Storage Temperature	Tstg	-30	-	+85	°C	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

6-2 Operating Conditions

(Ta=25°C)

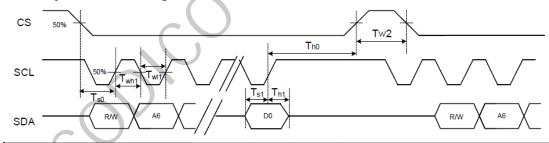
0-2 Operating	Conanno	115			(1a-	-43 ()
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply	VCC	-	3.0	3.3	3.6	Volt
Input Voltago	V _{IH}	-	0.7 *VCC		VCC	V
Input Voltage	V_{IL}	-	0		0.3*VCC	V
Power Supply Current for LCM	IDD	VCC=3.3V		TBD	-	mA
Ç			2,			



6-3 Timing Characteristics

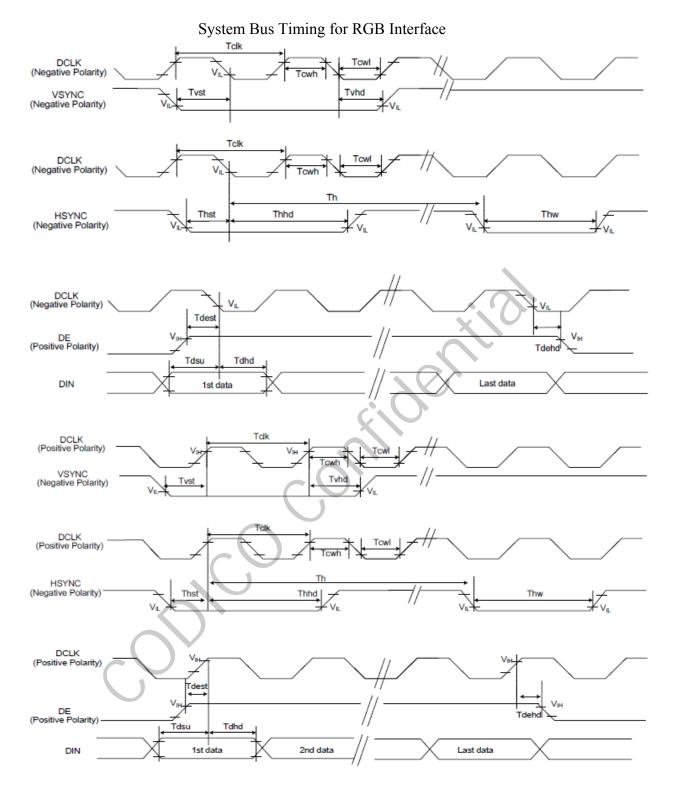
System Bus Timing for I2C Interface									
$SDA (In) + T_{BUF} + T_{LOW} + T_{HIGH}$ $SGL + T_{f} + T_{r}$									
SDA (Out)	Symbol	JISTA	Typ.	T _{SU,STO}	Unit	Conditions			
SCL Clock Frequency	FSCL	-	тур.	400	KHz	Conditions			
			-						
SCL Clock Low Period	TLOW	1300	-	-	ns				
SCL Clock High Period	THIGH	600	-	-	ns				
Signal Rise Time	Tr	20+0.1Cb	-	300	ns				
Signal Fall Time	Tf	20+0.1Cb	-	300	ns				
Start Condition Setup Time	TSU;STA	600	-	-	ns	·			
Start Condition Hold Time	THD;STA	600	-		ns				
Data Setup Time	TSU;DAT	100	-	-	ns				
Data Hold Time	THD;DAT	0	-	900	ns				
Setup Time for STOP Condition	TSU;STO	600		-	ns				
Bus Free Time Between a STOP and START	TBUF	100		-	ns				
Capacitive load represented by each bus line		Cb		400	pF				

System Bus Timing for 3-Wire SPI Interface



Item	Symbol	Min.	Тур.	Max.	Unit	Conditions
CS Input Setup Time	Ts0	50	-	-	ns	
Serial Data Input Setup Time	Ts1	50	-	-	ns	
CS Input Hold Time	Th0	50	-	-	ns	
Serial Data Input Hold Time	Th1	50	-	-	ns	
SCL Write Pulse High Width	Twh1	50	-	-	ns	
SCL Write Pulse Low Width	Twl1	50	-	-	ns	
SCL Read Pulse High Width	Trh1	300			ns	
SCL Read Pulse Low Width	Trl1	300			ns	
CS Pulse High Width	Tw2	400	-	-	ns	







ltem	Symbol	Min.	Тур.	Max.	Unit	Conditions
CLK Pulse Duty	Tclk	40	50	60	%	
HSYNC Width	Thw	2	-	-	DCLK	
VSYNC Setup Time	Tvst	12	-	-	ns	
VSYNC Hold Time	Tvhd	12	-	-	ns	
HSYNC Setup Time	Thst	12	-	-	ns	
HSYNC Hold Time	Thhd	12	-	-	ns	
Data Setup Time	Tdsu	12	-	-	ns	
Data Hold Time	Tdhd	12	-	-	ns	
DE Setup Time	Tdest	12	-	-	ns	
DE Hold Time	Tdehd	12	-	-	ns	



7. Optical Characteristics:

Itom	Item		Symbol Conditions		Specifications			Note
Iten	1	Symbol	Conditions	Min	Тур	Max	Unit	Note
Transmittance (With PL)		T(%)	-	-	6.2	-	-	-
Contrast Ratio		CR	⊕=0 Normal Viewing angle	-	800	-		(1) (2)
Response	time	TR+TF	_	-	30	40	ms	(1) (3)
	Hor.	Θx+		-	80	-		
Viewing		Өх-	CR≧10	-	80	-	deg.	
angle	Vor	θy+	$O_{\rm IX} = 10$	-	80	_	uey.	
	Ver.	θy-		_	80	-		$\boldsymbol{\mathcal{O}}$

Measuring Condition

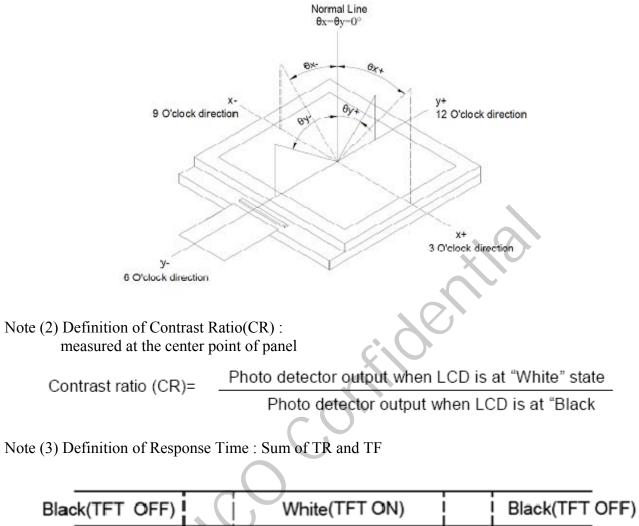
- 1. Measuring surrounding: dark room
- 2. Ambient temperature: $25\pm2^{\circ}C$
- 3. 30 min. Warm-up time.

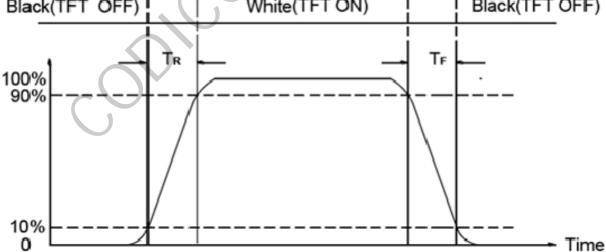
Color of CIE Coordinate:

asuring Condition Measuring surrounding: dark room Ambient temperature: 25±2°C 30 min. Warm-up time. olor of CIE Coordinate:								
Item		Symbol	Condition	Min.	Тур.	Max.		
		x		TBD	0.630	TBD		
	Red	y		TBD	0.352	TBD		
		x	$\theta=\varphi=0^\circ$	TBD	0.375	TBD		
Chromaticity	Green	у	LED Backlight	TBD	0.579	TBD		
Coordinates (Transmissive)		Х	Color Degree	TBD	0.142	TBD		
(Transmissive)	Blue	у		TBD	0.110	TBD		
	N71-:4	X		TBD	0.326	TBD		
	White	у		TBD	0.345	TBD		



Note (1) Definition of Viewing Angle :





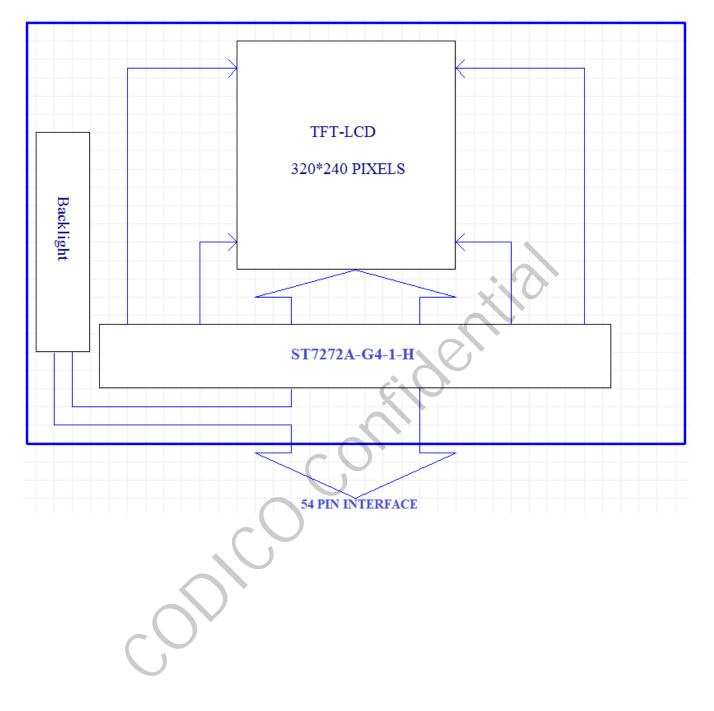


8. Interface Pin Assignment:

No.	Symbol	Function
1~2	LED-	Backlight LED Cathode input pin.
3~4	LED+	Backlight LED Anode input pin.
5	GND	Ground.
6	RESET	System reset pin.
7	NC	
8	NC	
9	NC	No connection.
10	NC	
11	NC	
12~35	B00~B23	Data Bus.
36	HSYNC	Horizontal Synchronous signal.
37	VSYNC	Vertical Synchronous signal.
38	DCLK	Data clock.
39~40	NC	No connection.
41~42	VCC	Power supply.
43	SPENA	Chip select for serial port use.
44	GND	Ground.
45	NC	No connection.
46	GND	Ground.
47,48	NC	No connection.
49	SPCK	Serial port Clock.
50	SPDA	Serial port Data input/output
51	NC	No connection.
52	DEN	Data enable signal.
53~54	GND	Ground.



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type): The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.
- 3. Data About LED Backlight:

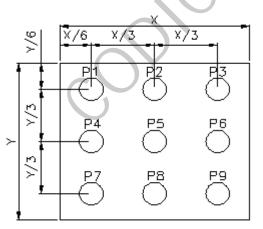
(Ta=25°C)

S. Dua Hood EED Duomign. (14 20 0						• • •)	
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	Ι		20		mA	V=19.2V	
Supply Voltage	V	16.2	19.2	20.4	V		
Luminous Intensity for LCM	IV	400	500	-	cd/m ²	If=20mA	2
Uniformity for LCM	-	70	-	-	%	II–20mA	3
Life Time	-	50000	-	->	Hr.		4
Color	White						

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)



Internal Circuit Diagram

CIRCUIT DIAGRAM B/L Electrical Circuit

(Effective spatial Distribution) Using aperture of 1°, distance 50cm



<u>11. Standard Specification for Reliability:</u> 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 85° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -30° C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 85°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30° C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60° C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
	Discharge	Contact: ± 2 KV 150pF/330 Ω 5 time

*Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11.2, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}$ C), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.



12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

- c. Test of Appearance Characteristics:
 - According to the individual specification to test the product.
- d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

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(i) Test method: According to ISO2859-1.General Inspection Level II take a single time.
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(ii) The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5

- Total defects: AQL = 2.5
- 12-3. Non- conforming Analysis & Deal With Manners
 - a. Non- conforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.

- (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
- (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

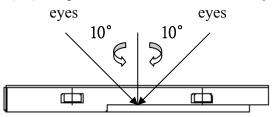


- 12-5. Standard of The Product Appearance Test
 - a. Manner of appearance test:

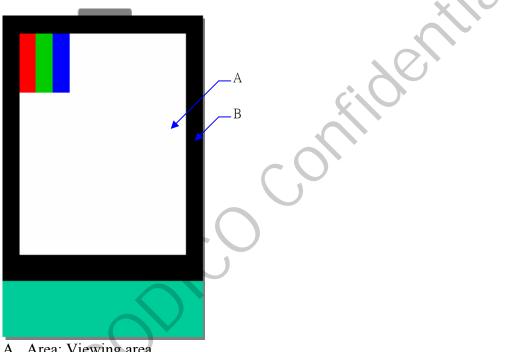
(i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.

- (ii) When test the model of transmissive product must add the reflective plate.
- (iii)The test direction is base on around 10° of vertical line.

(iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

(Outside viewing area)

- b. Basic principle:
 - (i) It will accord to the AQL when the standard can not be described.
 - (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
 - (iii) Must add new item on time when it is necessary.
 - c. Standard of inspection: (Unit: mm)



12-6. Inspection specification Defect out of viewing area can be neglected.

NO		viewing area can be negl		torion		AOT	
NO	Item	1 1 Missing vertical he		terion	antraat dafaat	AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 					
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or Five spots.2.2 Densely spaced: No2.3 Not visible through	o more than 5% ND filt	three spots within ter		2.5	
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As foll $\Phi = (X+Y) / 2$ * Densely spaced: No 3.2 Line type: (As following the fol	0 0 0 0 0 0 0	Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$ than two	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm. Acceptable Q'ty Accept no dense - 2	2.5	
				0.08 <w< td=""><td>Rejection</td><td></td></w<>	Rejection		
		* Dens	ely spaced:	No more than tw	o lines within 3mm.		



NO	Item	Criterion				AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	$Size 0$ $\Phi \leq 0.20 < 0$ $0.50 < 0$	$ \begin{array}{c} $	Acceptable Q'ty Accept no dense 3 2	2.5
			Tota	$0 < \Phi$ l Q'ty	0 3	
05	Scratches	Follow NO.3 -2 Line T	21			
06	Mura	Not visible through 5%	ND filter in 50% gra	ıy.		2.5
07	Chipped glass	k: Seal width L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel sur $\boxed{z: Chip thickness}$ y: $Z \le 1/2t$ $1/2t < z \le 2t$ \bigcirc Unit: mm \bigcirc If there are 2 or more 6.1.2 Corner crack:	t: Glass thickness a face and crack betwe y k Chip width Not over viewing area Not exceed 1/3k e chips, x is the total y : Chip width Not over viewing area Not exceed 1/3k	x: Chipx \leq x \leq length ofx \leq x \leq x \leq	e length	2.5



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length T.2 Protrusion over terminal: 7.2.1 Chip on electrode pad: Line Line Line Line Line Line Line Line	
		y: Chip widthx: Chip lengthz: Chip thickness $y \le 0.5mm$ $x \le 1/8a$ $0 < z \le t$	
		7.2.2 Non-conductive portion:	
08	Glass crack	y z z y z z z x	2.5
		y: Chip width x: Chip length z: Chip thickness	
	C	y≤L x≤1/8a 0< z≤t	



NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	РСВ、СОВ	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65 0.65
13	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept.	2.5 2.5
14	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion A				
		Symbols:x: Chip lengthy: Chip widthz: Chip thicknessk: Seal widtht: Touch Panel Total thicknessa: LCD sidelengthL: Electrode pad length14.1 General glass chip:14.1.1 Chip on panel surface and crack between panels:	AQL			
			2			
	Touch Panel	z: Chip thickness y: Chip width x: Chip length				
15		$Z \leq t \qquad \qquad$	2.5			
15	Chipped glass	⊙ Unit: mm	2.3			
		\odot If there are 2 or more chips, x is the total length of each chip				
		14.1.2 Corner crack:				
		X				
		z: Chip thickness y: Chip width x: Chip length				
		$ \begin{array}{ c c c c } \hline & \leq 1/2 \ k \ and \ not \ over \\ viewing \ area \end{array} & x \leq 1/8a \end{array} $				
		 ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 				



NO	Item	Criterion	AQL		
16	Touch Panel(Fish eye、dent and bubble on film)	SIZE(mm)Acceptable Q'ty $\Phi \leq 0.2$ Accept no dense $0.2 < D \leq 0.4$ 5 $0.4 < D \leq 0.5$ 2 $0.5 < D$ 0	2.5		
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	2.5		
18	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5		
19	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g			
20	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	0.65 0.65 0.65 0.65		



13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products could meet requirements of the environment.

YB's RoHS is introduce European Union Directive 2011/65/EU (ROHS) Requirements and Update.